

WHAT IS CLAIMED IS:

1. A method of manufacturing a display device, comprising the steps of:
 - forming a peeling layer on an element-forming substrate;
 - forming an insulating layer on said peeling layer;
 - forming a luminous element on said insulating layer;
 - bonding a fixed substrate on said luminous element by using a first adhesive;
 - exposing the entire substrate to a gas containing halogen fluoride after bonding said fixed substrate to thereby remove said peeling layer; and
 - bonding a bonding substrate to said insulating layer by using a second adhesive.
2. A method according to claim 1, wherein polyimide, acrylic, or epoxy resin is used as said first adhesive.
3. A method according to claim 1, wherein a material used for forming said bonding substrate is the same as that for forming said fixed substrate.
4. A method of manufacturing a display device, comprising the steps of:
 - forming a peeling layer on an element-forming substrate;
 - forming an insulating layer on said peeling layer;
 - forming a semiconductor element on said insulating layer;
 - forming a luminous element that is electrically connected to said semiconductor element;
 - bonding a fixed substrate on said luminous element by using a first adhesive;
 - exposing the entire substrate to a gas containing halogen fluoride after

bonding said fixed substrate to thereby remove said peeling layer; and

bonding a bonding substrate to said insulating layer by using a second adhesive.

5 5. A method according to claim 4, wherein polyimide, acrylic, or epoxy resin is used as said first adhesive.

6. A method according to claim 4, wherein a material used for forming said bonding substrate is the same as that for forming said fixed substrate.

10 7. A method of manufacturing a display device, comprising the steps of:

 forming a peeling layer on an element-forming substrate;

 forming an insulating layer on said peeling layer;

 forming active layers, a gate insulating layer, and gate electrodes over said

15 insulating layer;

 forming first openings in said gate insulating layer, said insulating layer, and said peeling layer;

 forming a first interlayer insulating layer to cover said gate electrodes;

 forming wirings and a pixel electrode on said first interlayer insulating layer;

20 forming second opening in said first interlayer insulating layer, said gate insulating layer, and said insulating layer to thereby expose said peeling layer;

 exposing the entire substrate to a gas containing halogen fluoride to thereby remove said peeling layer;

 forming a second interlayer insulating layer to cover said wirings and said

25 pixel electrode;

etching said second interlayer insulating layer to thereby expose said pixel electrode;

forming a luminous layer and a cathode on said pixel electrode;

bonding a fixed substrate on said cathode by using a first adhesive;

5 separating said element-forming substrate and said first interlayer insulating layer after bonding said fixed substrate; and

bonding a bonding substrate to said insulating layer by using a second adhesive.

10 8. A method according to claim 7, wherein polyimide, acrylic, or epoxy resin is used as said first adhesive.

9. A method according to claim 7, wherein a material used for forming said bonding substrate is the same as that for forming said fixed substrate.

15 10. A method of manufacturing a display device, comprising the steps of:
forming a peeling layer on an element-forming substrate;
forming an insulating layer on said peeling layer;
forming a first stripe electrode on said insulating layer;
20 bonding a fixed substrate having a second stripe electrode formed thereon on said element-forming substrate by a sealing member;
injecting a liquid crystal between said first stripe electrode and said second stripe electrode;

25 exposing the entire substrate to a gas containing halogen fluoride after injecting the liquid crystal to thereby remove said peeling layer; and

bonding a bonding substrate to said insulating layer by using a second adhesive.

11. A method according to claim 10, wherein polyimide, acrylic, or epoxy resin
5 is used as said first adhesive.

12. A method according to claim 10, wherein a material used for forming said bonding substrate is the same as that for forming said fixed substrate.

10 13. A method of manufacturing a display device, comprising the steps of:
forming a peeling layer on an element-forming substrate;
forming an insulating layer on said peeling layer;
forming active layers, a gate insulating layer, and gate electrodes on said
insulating layer;
15 forming a first interlayer insulating layer to cover said gate electrodes;
forming wirings and a pixel electrode on said first interlayer insulating layer;
bonding a fixed substrate that is provided with an opposing electrode on said
element-forming substrate by a sealing member;
injecting a liquid crystal between said pixel electrode and said opposing
20 electrode;
exposing the entire substrate to a gas containing halogen fluoride after
injecting the liquid crystal to thereby remove said peeling layer; and
bonding a bonding substrate to said insulating layer by using a second
adhesive.

14. A method according to claim 13, wherein polyimide, acrylic, or epoxy resin is used as said first adhesive.

15. A method according to claim 13, wherein a material used for forming said
5 bonding substrate is the same as that for forming said fixed substrate.